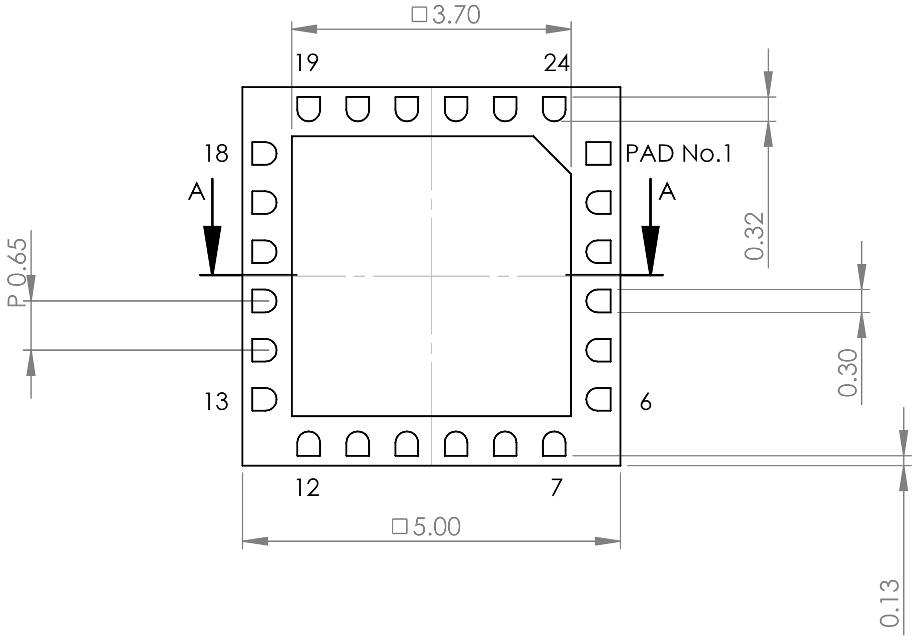
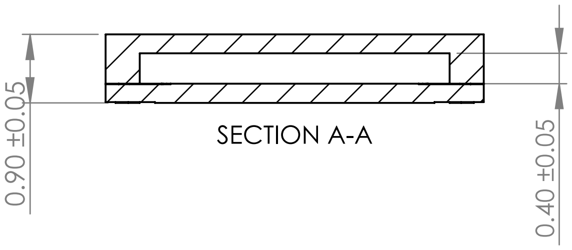
Package Dimensions:

Package Dimensions
QFN 5x5(24 Pin)

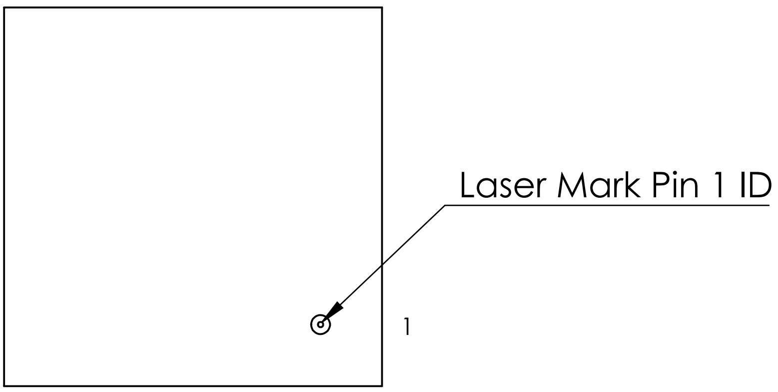
Bottom View



Side Section View



Top View



Notes:
1. Substrate material Mitubishi HL832NS(LC) S-glass
2. Lid material Rogers RO4003
3. Top substrate layout, standard iNPACK design customized per customers request
4. EM and thermal simulation based designs are available as customized solutions
5. Sealing- near hermetic adhesive
6. Marking per customers request
7. Center pad is GND
8. CuMo / Cu coin can be embedded at GND pad or fill Cu via stracture
9. Conforms to JEDEC standard JESD-30 MO-220
10. All dimensions are in millimeters

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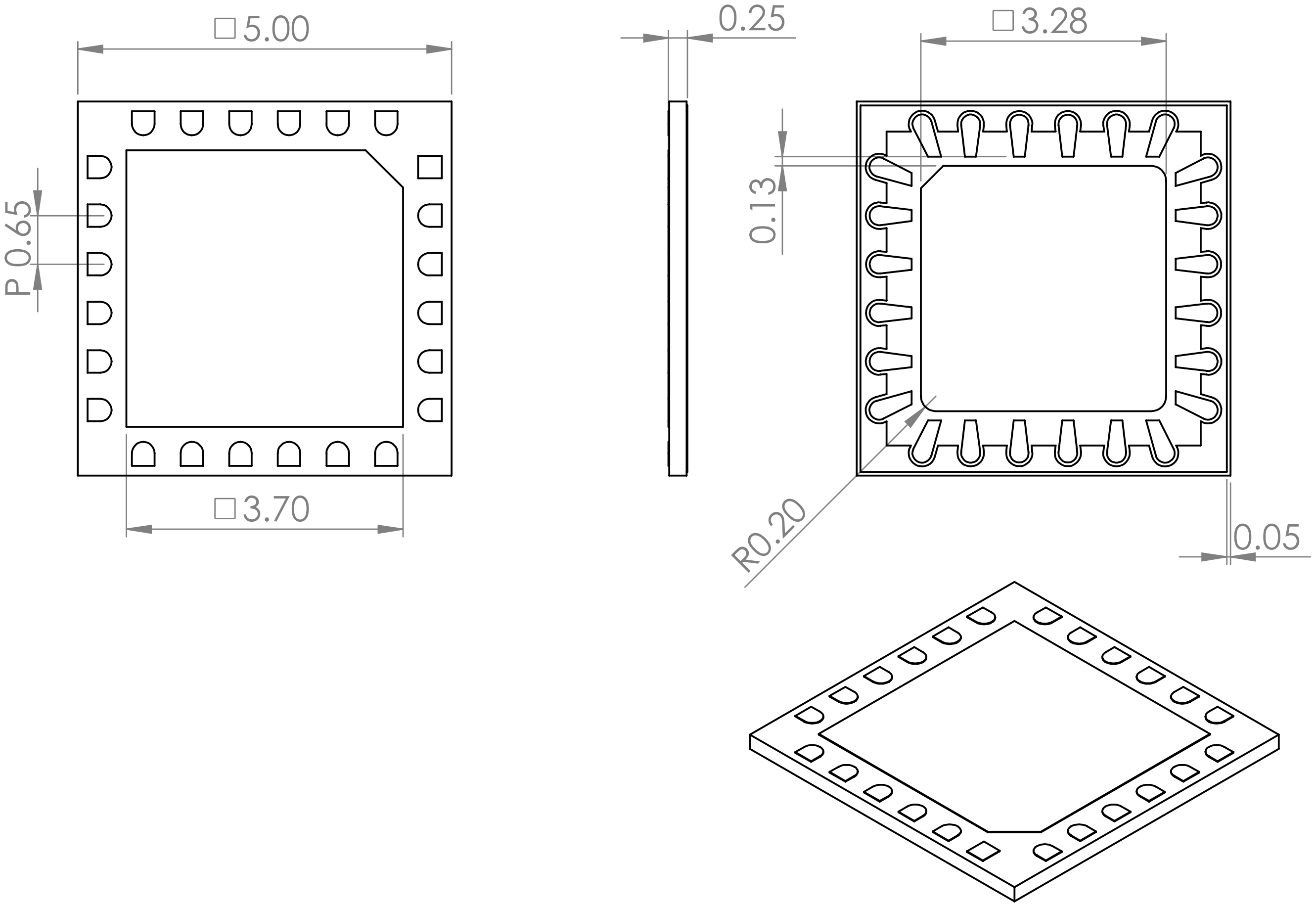
Substrate 5x5 24 :



Lid 5x5 :